

**ERF RA**

Lead material : RA005~RA090 Tin plated copper,24 AWG.

RA110~RA375 Tin plated copper, 20 AWG.

Soldering characteristics: MIL-STD-202, Method 208E.

Insulating coating: Flame retardant epoxy, meet UL-94V-0 requirement.

**ERF RN**

Lead material : RN010~RN090 Tin plated copper,24 AWG.

RN110~RN375 Tin plated copper,20 AWG.

Soldering characteristics: MIL-STD-202, Method 208E.

Insulating coating: Flame retardant epoxy, meet UL-94V-0 requirement.

**ERF RB**

Lead material : RB090~RB250 Tin plated copper, 24 AWG.

RB300~RB900 Tin plated copper, 20 AWG.

Soldering characteristics: MIL-STD-202, Method 208E.

Insulating coating: Flame retardant epoxy ,meet UL-94V-0 requirement.

**ERF RG**

Lead material : RG250-16 Tin plated copper,24 AWG.

RG300-16~ RG11A-16 Tin plated copper,20 AWG.

RG12A-16~RG14A-16 Tin plated copper,18 AWG.

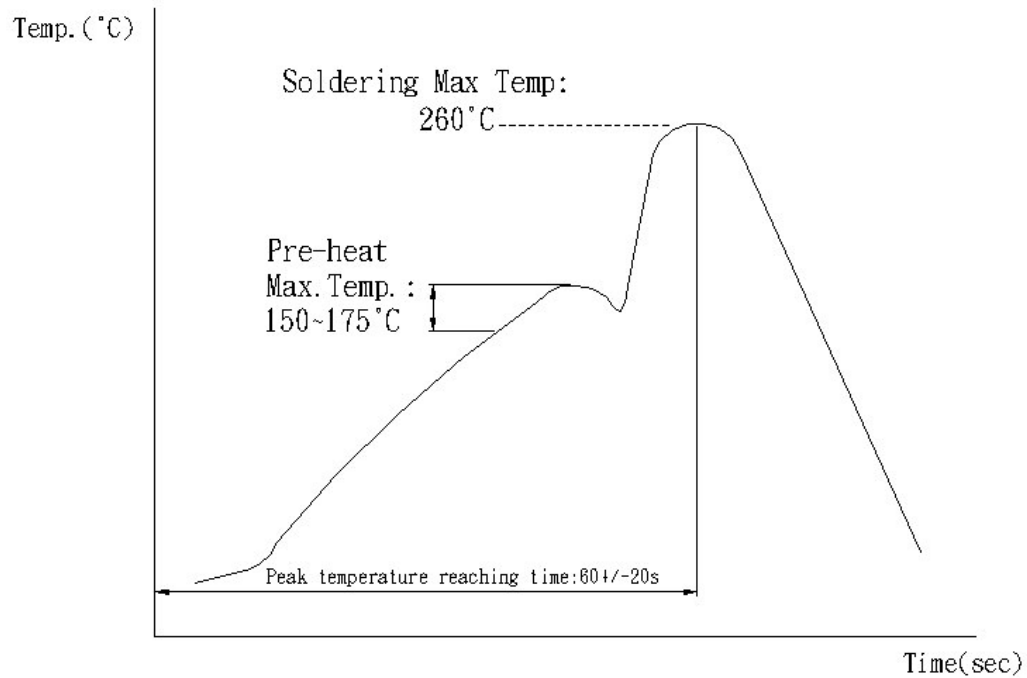
Soldering characteristics:MIL-STD-202, Method 208E.

Insulating coating:Flame retardant epoxy ,meet UL-94V-0 requirement.

**Through Hole Type:**

Wave soldering condition:

Refer to Wave Soldering Temperature Profile. **(260±5°C for 5±1 seconds)**



### ERF SD / ERF SL

Lead material: Pure Tin Plated Ni/Cu (Lead Free)

### SOLDER REFLOW (LEAD FREE)

1. Suggested reflow methods: IR, vapor phase oven, hot air oven.
2. Recommended maximum paste thickness is 0.25mm.
3. Devices are not designed to wave soldered to the bottom side of the board.

### CAUTION:

If reflow temperatures exceed the recommended Profile, devices may not meet the performance requirements.

